1 Characteristics

Table 1. Absolute maximum ratings T_{amb} = 25 °C

Symbol	Parameter		Value	Unit
V_{PP}	Peak pulse voltage	IEC 61000-4-2 contact discharge	8	kV
		IEC 61000-4-2 air discharge	20	
T_j	Operating junction temperature range		-40 to +150	°C
T_{stg}	Storage temperature range		-65 to +150	°C
T_L	Maximum lead temperature for soldering during 10 s		260	°C

Table 2. Electrical characteristics T_{amb} = 25 °C

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
V_{BR}	I_R = 1 mA	6.0			V
I_{RM}	V_{RM} = 3.0 V			70	nA
V_{CL}	I_{PP} = 1 A, 8/20 µs			15	V
CI/O - I/O	VI/O = 0 V, F = 1 MHz, V_{OSC} = 30 mV		0.3	0.4	pF
CI/O - GND	VI/O = 0 V, F = 1 MHz, V_{OSC} = 30 mV		0.6	0.8	pF
f_C	-3dB		8.7		GHz
Z_{diff}	Time domain reflectometry: t_r = 200 ps (10 - 90%), $Z_{0\ DIFF}$ = 100 Ω	85	100	115	Ω

1.1 On-board measurements

Figure 1. Leakage current versus junction temperature (typical values)

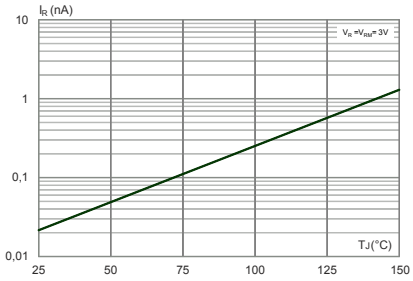


Figure 2. S21 attenuation measurement

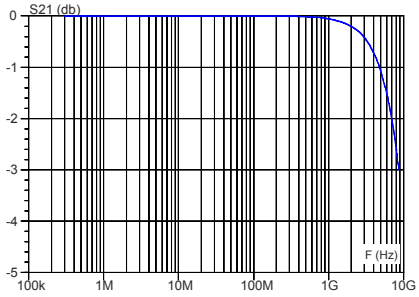


Figure 3. Differential impedance (Zdiff)

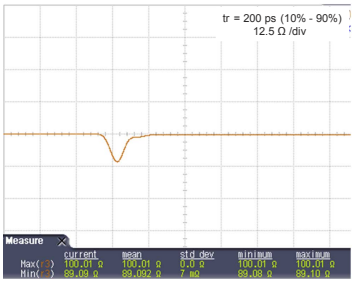
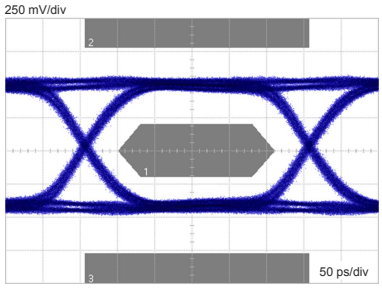


Figure 5. Eye diagram - HDMI mask at 3.4 Gbps per channel



1. *HDMI specification conditions. This information can be provided for other applications. Please contact your local ST office.*

Figure 7. ESD response to IEC 61000-4-2 (+8 kV contact discharge)

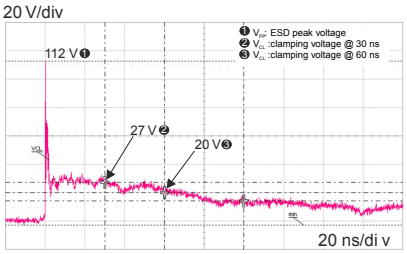
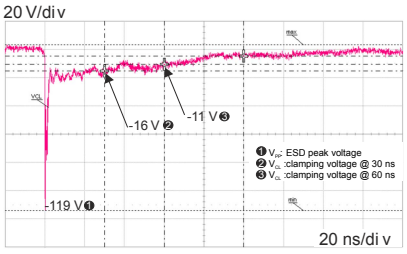


Figure 8. ESD response to IEC 61000-4-2 (-8 kV contact discharge)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 µQFN-10L dimension values

- Epoxy meets UL94, V0
- Lead-free package

Figure 9. µQFN-10L dimension definitions

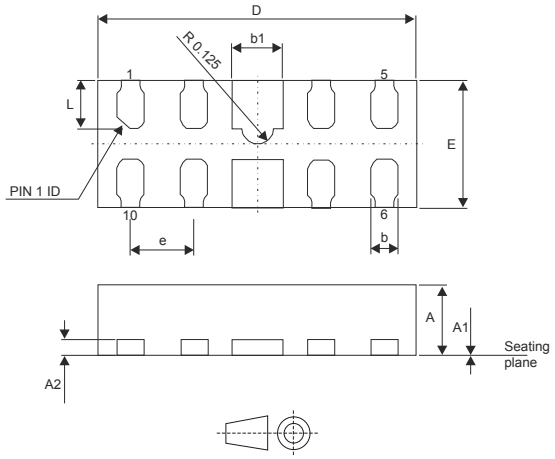


Table 3. µQFN-10L dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.40	0.47	0.50	0.018	0.018	0.020
A1	0.00	0.00	0.05	0.00	0.000	0.002
A2		0.13			0.005	
b	0.15	0.20	0.25	0.006	0.008	0.009
b1	0.35	0.40	0.45	0.014	0.016	0.041
D	2.40	2.50	2.60	0.094	0.098	0.102
E	0.90	1.00	1.10	0.035	0.039	0.043
e		0.50			0.206	
L	0.33	0.38	0.43	0.012	0.015	0.017
aaa		0.08			0.003	
bbb		0.10			0.004	

Figure 10. Footprint recommendations (dimensions in mm)

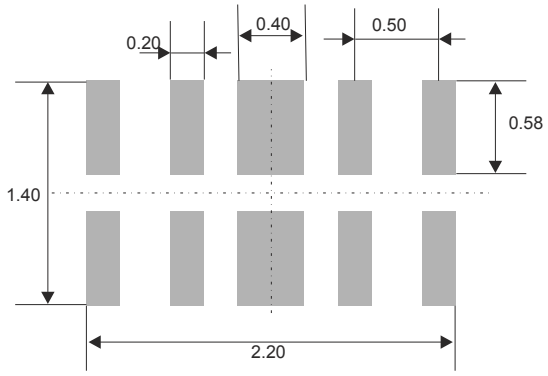
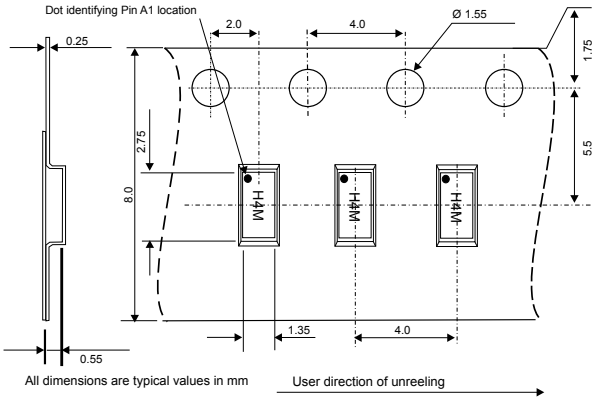


Figure 11. Marking

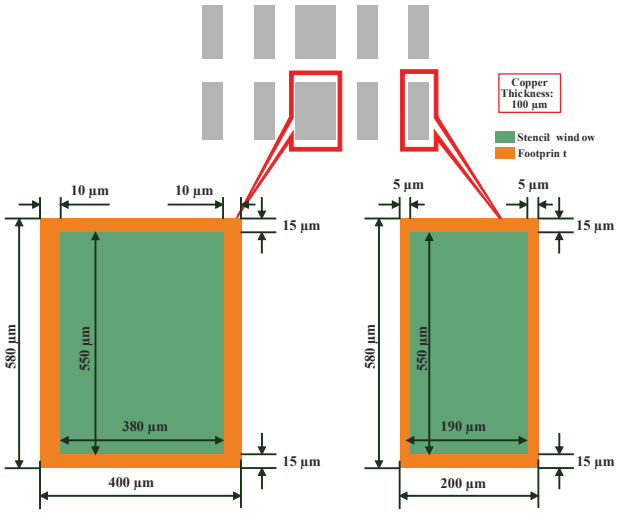
Note: Product marking may be rotated by 180° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

Figure 12. µQFN-10L tape and reel specification



3 Recommendation on PCB assembly

Figure 13. **µQFN-10L dimension definitions**



3.1 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. “No clean” solder paste is recommended.
3. Offers a high tack force to resist component movement during high speed.
4. Solder paste with fine particles: powder particle size is 20-45 µm.

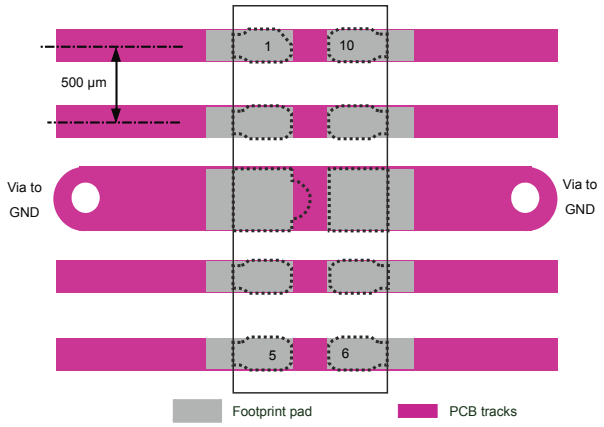
3.2 Placement

1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
3. Standard tolerance of ±0.05 mm is recommended.
4. 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

3.3 PCB design preference

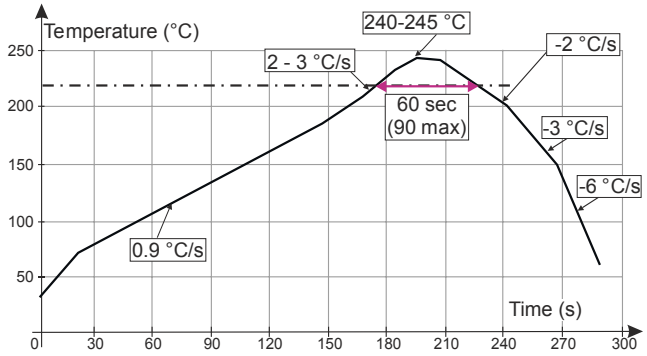
1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. A symmetrical layout is recommended, to avoid any tilt phenomena caused by asymmetrical solder paste due to solder flow away.

Figure 14. Printed circuit board layout recommendations



3.4 Reflow profile

Figure 15. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement.

Note: Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

4 Ordering information

Figure 16. **Ordering information scheme**

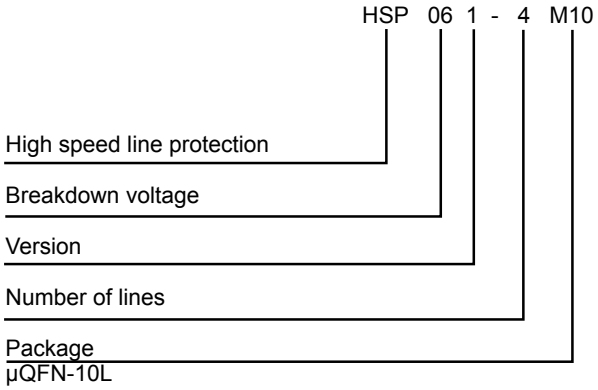


Table 4. **Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
HSP061-4M10	H4M	µQFN-10L	3.27 mg	3000	Tape and reel

Revision history

Table 5. **Document revision history**

Date	Version	Changes
05-Sep-2012	1	Initial release.
18-Oct-2012	2	Updated VPP in Table 1.
17-Jun-2014	3	Updated Figure 12 and reformatted to current standard.
13-Feb-2018	5	Added a note for Figure 11. Marking.